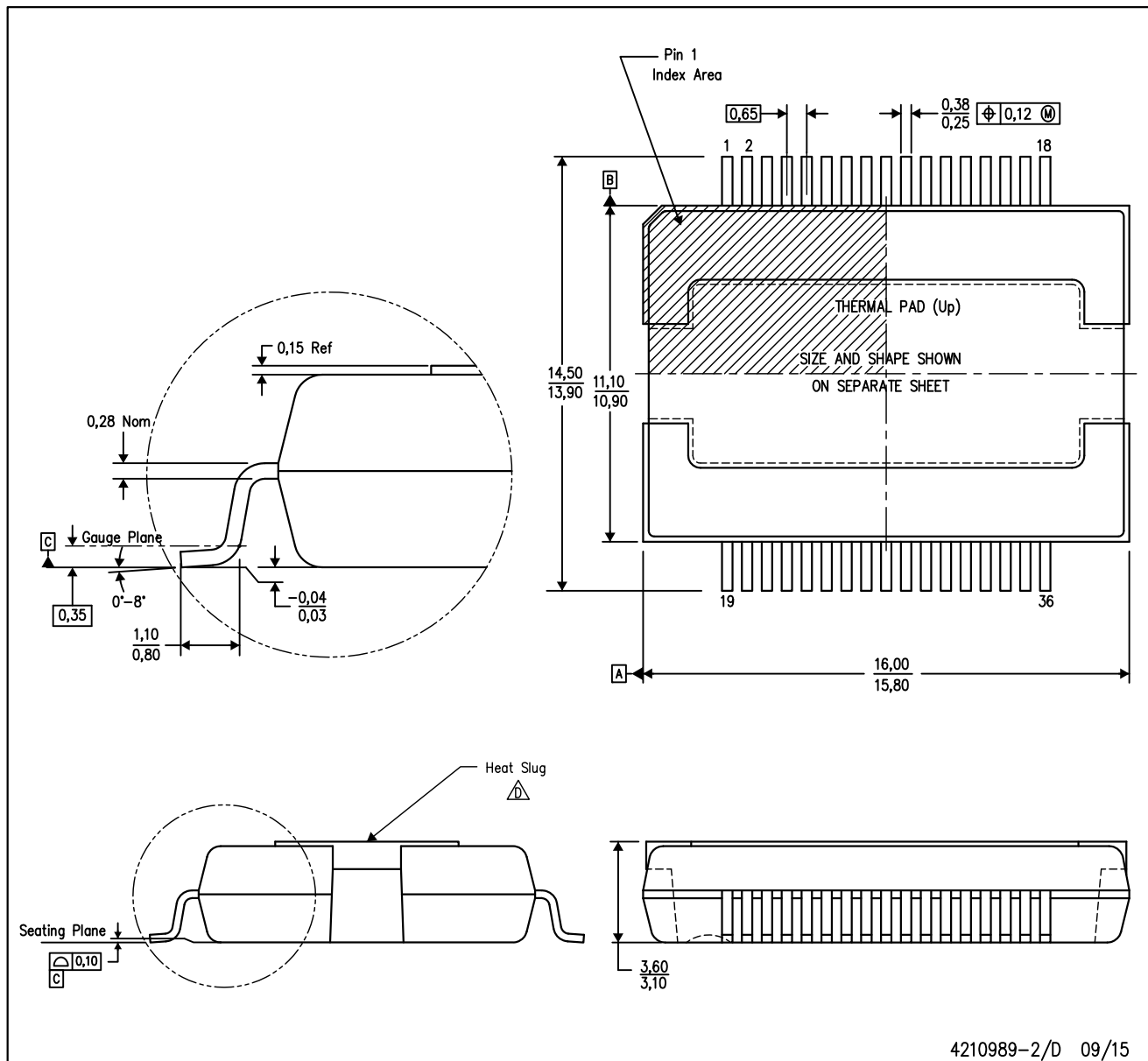



DKE (R-PDSO-G36)

PLASTIC SMALL OUTLINE



4210989-2/D 09/15

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.15mm.
 -  The package thermal performance is optimized for conductive cooling with attachment to an external heat sink.
 - E. See the product data sheet for details regarding the exposed thermal pad dimensions.

PowerPAD is a trademark of Texas Instruments.

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